

High Speed Infrared Emitting Diodes, 940 nm, GaAlAs, MQW

VSMB294008RG

VSMB294008G


DESCRIPTION

VSMB294008 series are infrared, 940 nm emitting diodes in GaAlAs multi quantum well (MQW) technology with high radiant power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

APPLICATIONS

- Data transmission
- Miniature light barrier
- Photointerrupters
- Optical switch
- Control and drive circuits
- Shaft encoders

FEATURES

- Package type: surface-mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8
- Peak wavelength: $\lambda_p = 940$ nm
- High reliability
- High radiant power
- High radiant intensity
- Angle of half intensity: $\phi = \pm 7^\circ$
- Low forward voltage
- Suitable for high pulse current operation
- Terminal configurations: gullwing or reserve gullwing
- Package matches with detector VEMD2000X01 series
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN FREE
GREEN
(IS-2008)

PRODUCT SUMMARY

COMPONENT	I _e (mW/sr)	ϕ (°)	λ_p (nm)	t _r (ns)
VSMB294008RG	70	± 7	940	15
VSMB294008G	70	± 7	940	15

Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMB294008RG	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing
VSMB294008G	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25$ °C, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V _R	5	V
Forward current		I _F	100	mA
Surge forward current	$t_p = 100$ μ s	I _{FSM}	500	mA
Power dissipation		P _V	160	mW
Junction temperature		T _j	100	°C
Operating temperature range		T _{amb}	-40 to +85	°C
Storage temperature range		T _{stg}	-40 to +100	°C
Soldering temperature	according to fig. 10, J-STD-020	T _{sd}	260	°C
Thermal resistance junction/ambient	J-STD-051, leads 7 mm, soldered on PCB	R _{thJA}	250	K/W

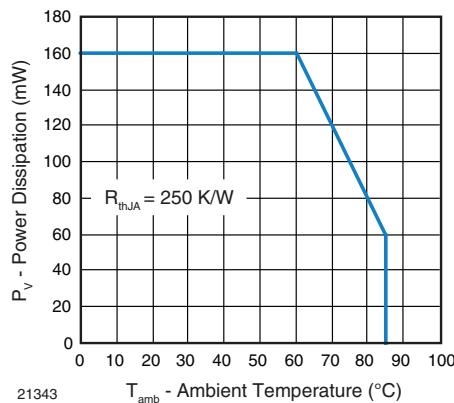


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

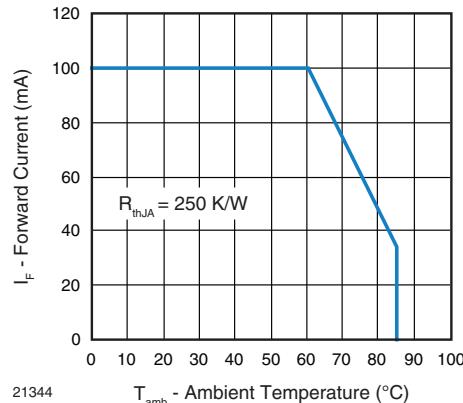


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS ($T_{amb} = 25$ °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100$ mA, $t_p = 20$ ms	V_F	1.15	1.45	1.75	V
	$I_F = 500$ mA, $t_p = 100$ µs	V_F	-	1.8	-	V
Temperature coefficient of V_F	$I_F = 100$ mA	TK_{VF}	-	-0.64	-	mV/K
Reverse current	$V_R = 5$ V	I_R	-	-	10	µA
Junction capacitance	$V_R = 0$ V, $f = 1$ MHz, $E = 0$ mW/cm ²	C_J	-	38	-	pF
Radiant intensity	$I_F = 100$ mA, $t_p = 100$ µs	I_e	30	70	115	mW/sr
	$I_F = 500$ mA, $t_p = 100$ µs	I_e	-	260	-	mW/sr
Radiant power	$I_F = 100$ mA, $t_p = 100$ µs	ϕ_e	-	40	-	mW
Temperature coefficient of radiant power	$I_F = 100$ mA	$TK\phi_e$	-	-0.43	-	%/K
Angle of half intensity		ϕ	-	± 7	-	°
Peak wavelength	$I_F = 30$ mA	λ_p	920	940	960	nm
Spectral bandwidth	$I_F = 30$ mA	$\Delta\lambda$	-	25	-	nm
Temperature coefficient of λ_p	$I_F = 30$ mA	$TK\lambda_p$	-	0.25	-	nm/K
Rise time	$I_F = 100$ mA, 20 % to 80 %	t_r	-	15	-	ns
Fall time	$I_F = 100$ mA, 20 % to 80 %	t_f	-	15	-	ns
Cut-off frequency	$I_{DC} = 70$ mA, $I_{AC} = 30$ mA pp	f_c	-	23	-	MHz

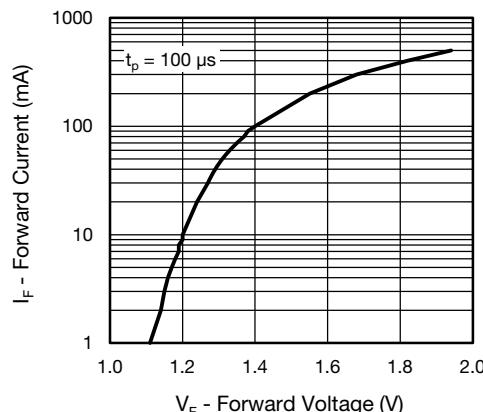
TYPICAL CHARACTERISTICS ($T_{amb} = 25^{\circ}\text{C}$, unless otherwise specified)


Fig. 3 - Forward Current vs. Forward Voltage

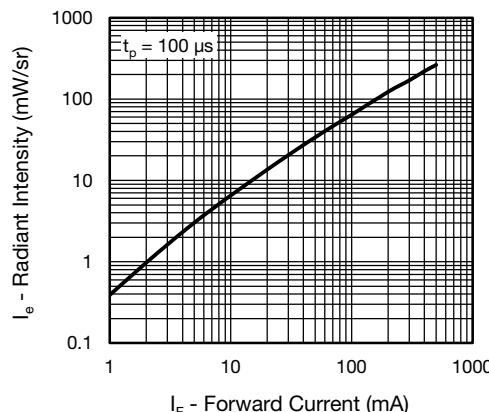


Fig. 6 - Radiant Intensity vs. Forward Current

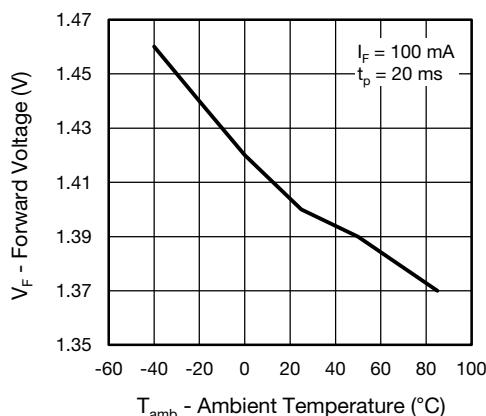


Fig. 4 - Forward Voltage vs. Ambient Temperature

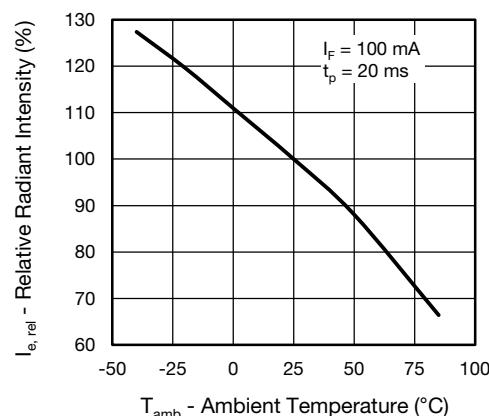


Fig. 7 - Radiant Intensity vs. Ambient Temperature

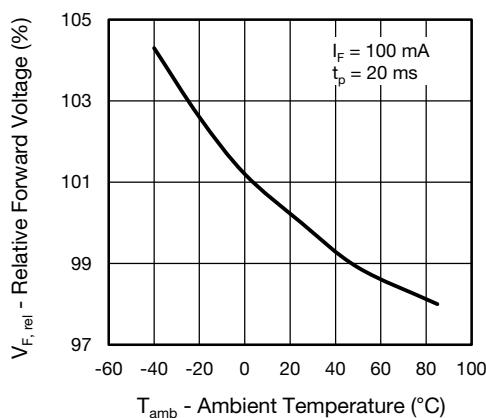


Fig. 5 - Relative Forward Voltage vs. Ambient Temperature

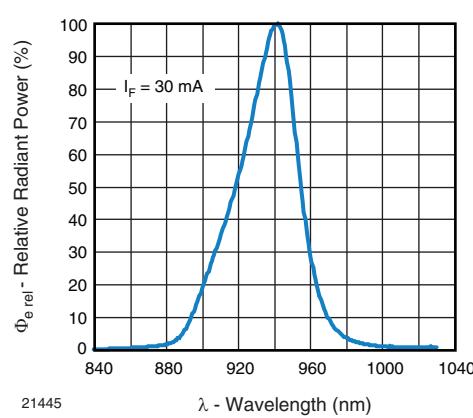
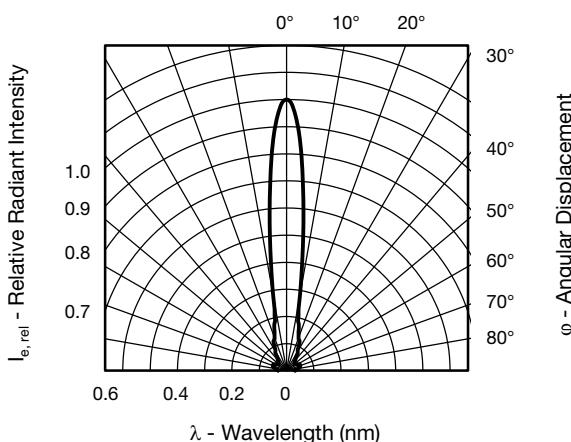


Fig. 8 - Relative Radiant Power vs. Wavelength



SOLDER PROFILE

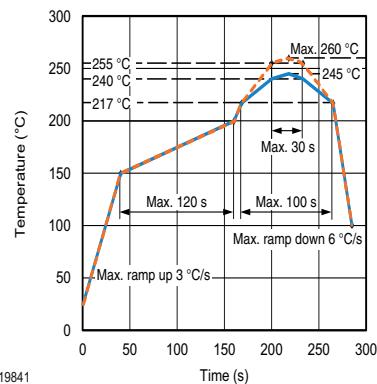


Fig. 10 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

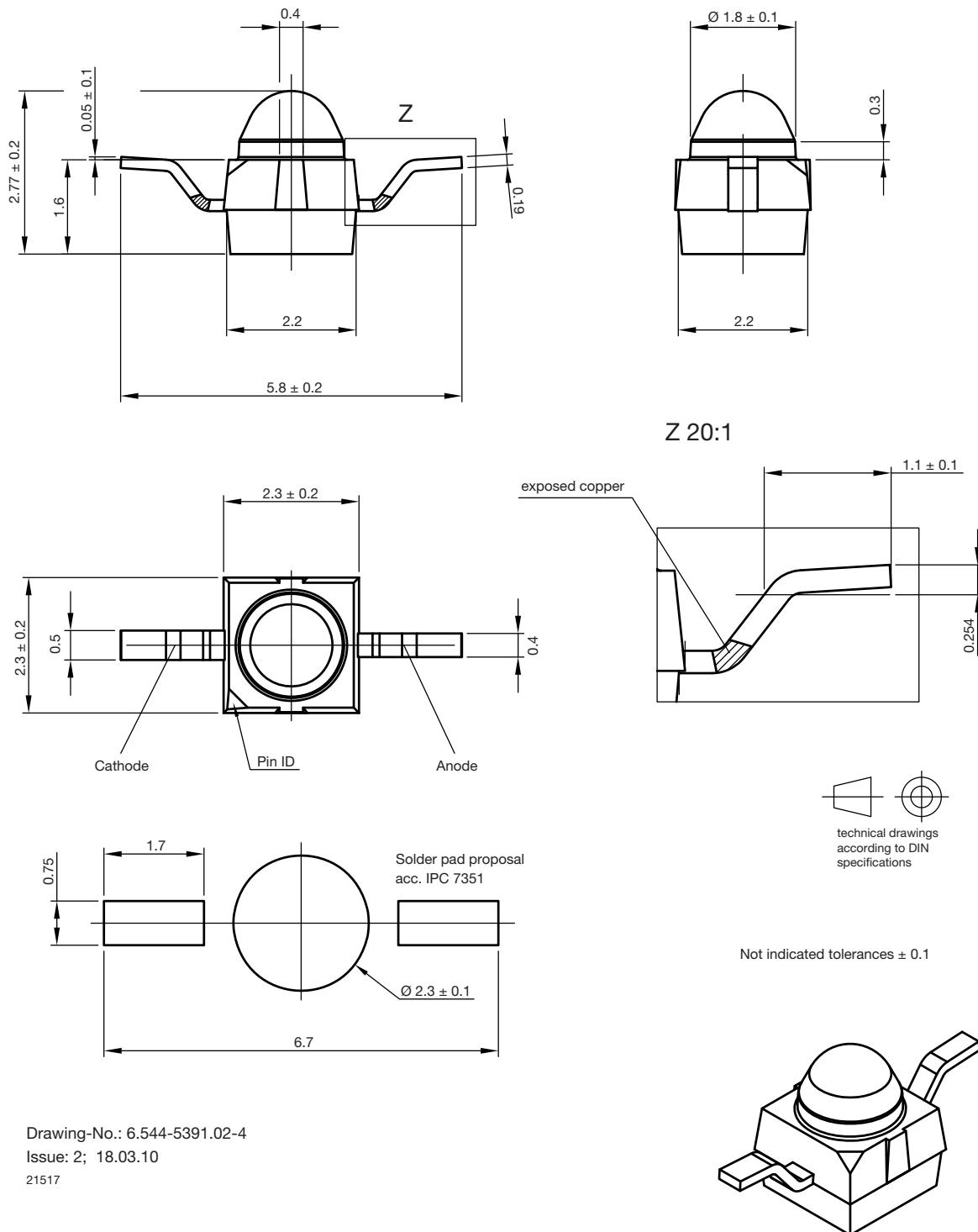
Floor life: 4 weeks

Conditions: $T_{amb} < 30^{\circ}\text{C}$, RH < 60 %

Moisture sensitivity level 2a, acc. to J-STD-020.

DRYING

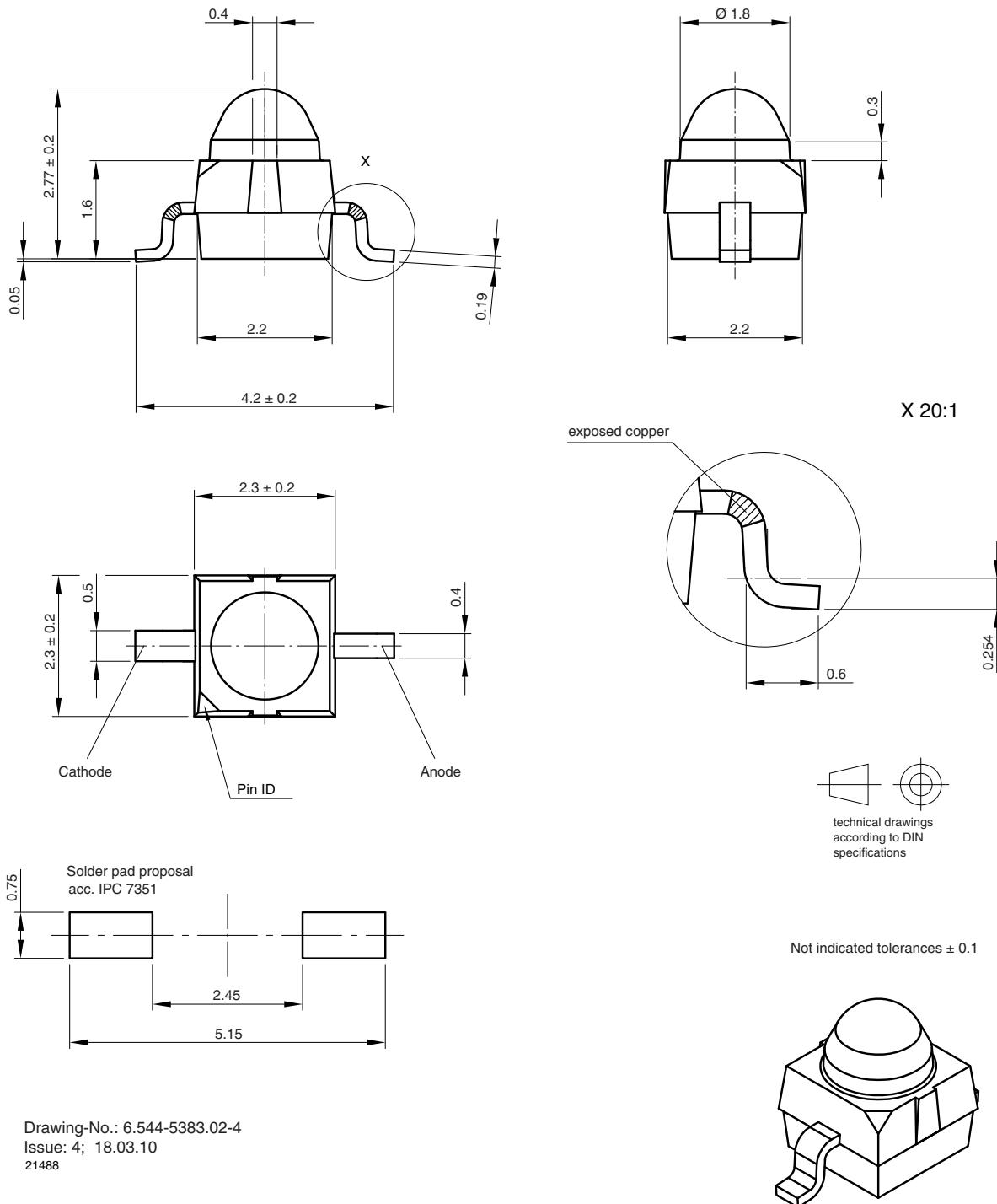
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

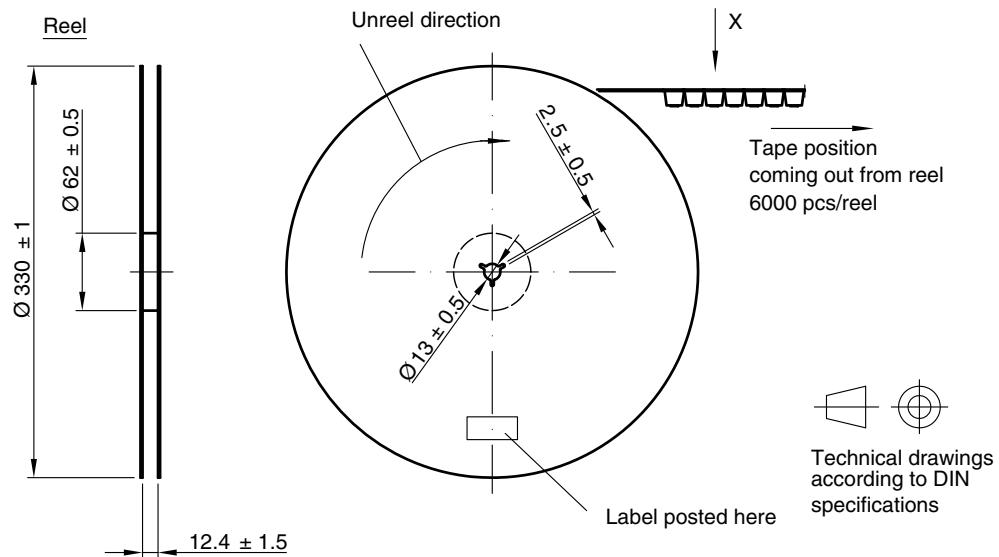
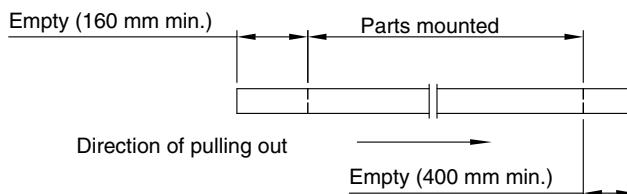
PACKAGE DIMENSIONS in millimeters: **VSMB294008RG**


Drawing-No.: 6.544-5391.02-4

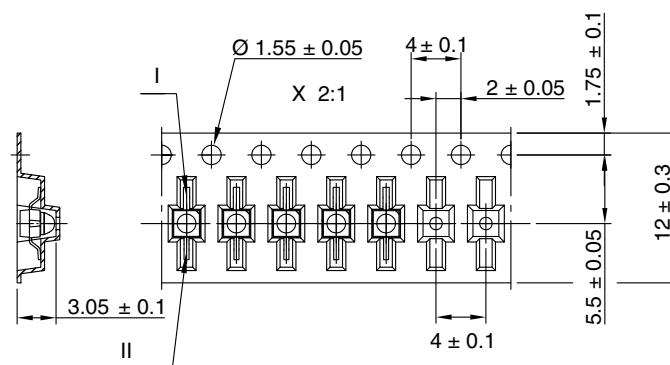
Issue: 2; 18.03.10

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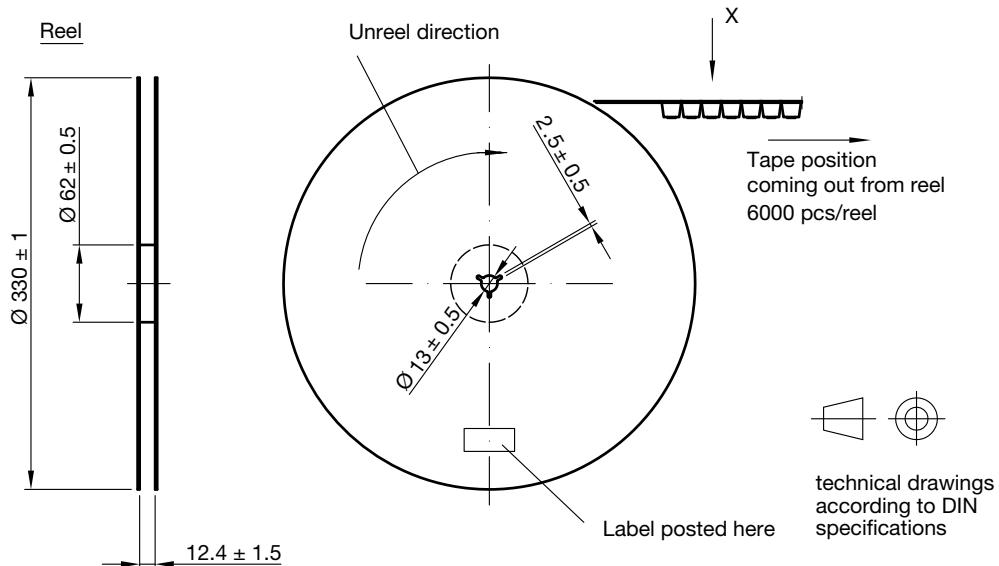
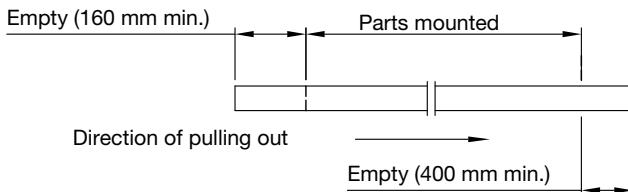
PACKAGE DIMENSIONS in millimeters: **VSMB294008G**


TAPING AND REEL DIMENSIONS in millimeters: **VSMB294008RG**

Leader and trailer tape:

Terminal position in tape

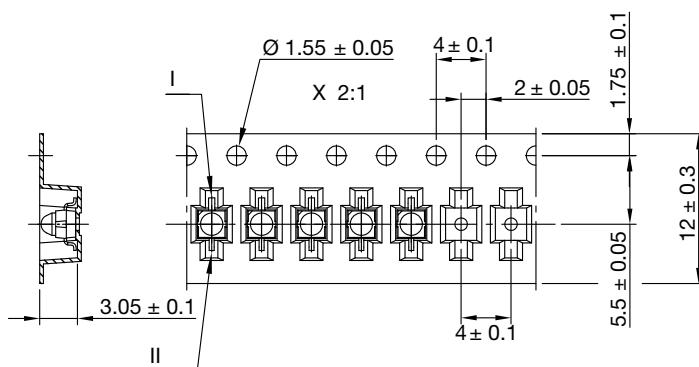
Device	Lead I	Lead II
VEMT2000		
VEMT2500	Collector	Emitter
VEMD2000		
VEMD2500		
VSMB2000	Cathode	Anode
VSMG2000		
VSMY2850RG	Anode	Cathode



Drawing-No.: 9.800-5100.01-4
Issue: 2; 18.03.10
21572

TAPING AND REEL DIMENSIONS in millimeters: **VSMB294008G**

Leader and trailer tape:

Terminal position in tape

Device	Lead I	Lead II
VEMT2020	Collector	Emitter
VEMT2520		
VSMB2020		
VSMG2020	Cathode	Anode
VEMD2020		
VEMD2520		
VSMY2850G	Anode	Cathode
VSMB294008GC		



Drawing-No.: 9.800-5091.01-4

Issue: 3; 18.03.10

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